Aces Electronic Co., Ltd.

Product Specification

Title ： 1.25 mm Pitch SMT Wire to Board Terminal

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1. Scope

This specification covers Aces's 1.25 mm pitch wire to board terminal.

P/N ： 88267 T seriers.

2. Ratings and Applicable Wires

2.1 Rated Voltage (Max) : 200 V【AC(rms)/DC】

2.2 Rated Current (Max) and Applicable wires :

AWG # 28	1.0 A【AC(rms)/DC】
AWG # 30	1.0A【AC(rms)/DC】
AWG # 32	0.8 A【AC(rms)/DC】

2.3 Ambient Temperature Range : —55℃ ~ ＋85℃*1

*1：Including terminal temperature rise.

3. Performance

3.1 Electrical Performance

Contact Resistance	Mate connectors, measure by dry circuit, 20m V Max., 10m A (JIS C5402 5.4)	20 m Ω Max.
Insulation Resistance	Mate connectors, apply 500 V DC between adjacent terminal or ground (JIS C5402 5.2 / MIL-STD-202 Method 302)	100 MΩ Min.
Dielectric Strength	Mate connectors, apply 500 V AC(rms) for 1 minute between adjacent terminal or ground (JIS C5402 5.1/MIL-STD-202, Method 301)	No Breakdown.
Contact Resistanc on Crimped Portic	The applicable wire shall be crimped on to the terminal, measure by dry circuit, 20m V Max., 10mA.	5 m Ω Max.

3.2 Mechanical Performance

Insertion and Withdrawal Force	Insert and withdraw connectors at the speed rate of 25 ± 3mm/min.	See item 5
Crimping Pull Out Force	Fix the crimped terminal, apply axial pull out force on the wire at speed rate of 25 ± 3 mm/min. (JIS C5402 6.8)	AWG # 28： 9.8 N〔1.0 kgf〕MIN. AWG # 30： 4.9 N〔0.5kgf〕MIN. AWG # 32： 3.0 N〔0.3kgf〕MIN.
Terminal Insertion Force	Insert the crimped terminal into the housing	9.8 N〔1.0 kgf〕MAX.
Terminal / Housing Retention Force	Apply axial pull out force at the speed rate of 25 ± 3 mm/minute on the terminal assembled in the housing	4.9 N〔0.5kgf〕MIN.
Fitting nail / Housi Retention Force	Apply axial push force at the speed rate of 25 ± 3 mm/minute on the fitting nail assembled in the housing.	4.0 N〔0.4kgf〕MIN.

3.3 Environmental Performance and Others

Repeated Insertion / Withdra	When mated up to 50 cycles, repeatedly by the rate of 10 cycles/min	Contact Resistance： 40 m Ω Max.
Temperature Rise	Carrying rated current load (UL 498)	Temperature rise： 30℃ Max
Vibration	Amplitude ：1.5 mm P-P Sweep time：10-55-10 Hz in 1 minute Duration：2 hrs in each X.Y.Z. axes (MIL-STD-202, Method 201)	Appearance： No Damage Contact Resistance： 40 m Ω Max. Discontinuity： 1 μsec. Max.
Shock	490m/s^2〔50G〕, 3 strokes in each X.Y.Z.axes. (JIS C0041 / MIL-STD-202, Method 213)	Appearance： No Damage Contact Resistance： 40 m Ω Max. Discontinuity： 1 μsec. Max.

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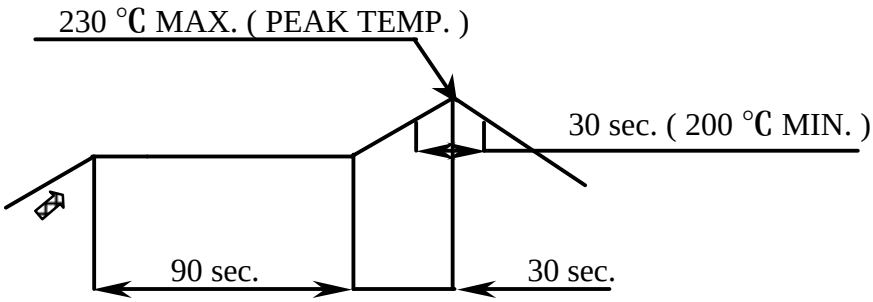
Heat Resistan	85 ± 2°C, 96 hrs. (JIS C0021 /MIL-STD-202, Method 108)	Appearance ：No Damage Contact Resistance： 40 m Ω Max.
Cold Resistan	-55 ± 3°C, 96 hrs (JIS C0020)	Appearance：No Damage Contact Resistance： 40 m Ω Max.
Humidity	Temperature：60 ± 2°C Relative humidity ：90 ~ 95 % Duration：96 hrs. (JIS C0022/MIL-STD-202 Method 103)	Appearance ：No Damage Contact Resistance： 40 m Ω Max. Insulation Resistance： 10 M Ω Min.
Temperature Cycling	5 cycles of： (a) -55 ± 3°C, 30 minutes (b) ＋85 ± 2°C, 30 minutes (JIS C0025)	Appearance：No Damage Contact Resistance： 40 m Ω Max.
Salt Spray	96 hours exposure to a salt spray from the 5 ± 1% solution at 35 ± 2°C. (JIS C5023/MIL-STD, -202 Method 101)	Appearance：No Damage Contact Resistance： 40 m Ω Max.
SO_2 Gas	24 hrs exposure to 50 ± 5 ppm. SO_2 gas at 40 ± 2°C	Appearance：No Damage Contact Resistance： 40 m Ω Max.
Solder-Ability	Soldering time：3 ± 0.5 Sec Solder temperature：230 ± 5°C	Solder Wetting：95% of immersed area must show no voids, pin holes
Resistance to Soldering Hea	Soldering time：3 ± 0.5 Sec Solder temperature：350 ± 5°C 0.5 mm from terminal tip and fitting nail tip	Appearance：No Damage

4. Insertiion / Withdrawal Force

No. of CKT	UNIT	Insertion			Withdrawal (MIN.)		
		1st	6 th	50 th	1st	6 th	50 th
2	N kgf	58.8 {6.00}	58.8 {6.00}	58.8 {6.00}	9.8 {1.00}	9.8 {1.00}	9.8 {1.00}
30	N kgf	83.3 {8.50}	83.3 {8.50}	83.3 {8.50}	14.7 {1.50}	14.7 {1.50}	14.7 {1.50}

5. INFRARED REFLOW CONDITION



(Pre-heat 150 ℃ MAX (Reflow)

TEMPERATURE CONDITION GRAPH
(TEMPERATURE ON BOARD PATTERN SIDE)

NOTE：Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, p.c. boards, and so on.